# Product Change Notification	Date February 9, 2023
Product	Digi ConnectCore MP157 Development Kit and SOMs

Reason for Change:

☐ Technical Requirement	☐ Product Transition
☐ Customer Requirement	☐ Product Discontinuation
☐ Quality Improvement	☐ Product Enhancement
☐ Change of Production Location	☒ Other (MOQ and MSL updates)

Audience	Channel Partners and Direct Customers
Description of Change	With the aim of promoting the introduction of this new Digi ConnectCore MP1 system-on-modules (SOM) family and to support design-in activities with small amounts of SOMs needed for prototyping, the minimum order quantity (MOQ) has been reduced to 1 unit for all SOM variants. Additionally, the Moisture Sensitivity Level (MSL) for the development kit has been corrected from MSL 3 to MSL N/A. Finished development kits are not going through a Surface Mount Technology (SMT) manufacturing process, therefore development kits are not sensitive to moisture. MSL ratings are for components or modules which are intended to be used in a manufacturing process.

Affected Part Numbers	CC-WST-DW69-NM CC-ST-DW69-ZM CC-WMP157-KIT

Additional Notes	The objective of the MOQ change is to enable customers for early evaluation and prototyping with small amounts of SOMs, rather than production quantities, at the current stage of the product lifecycle. MOQs will be raised again at a later stage of the product lifecycle.

Authorization	Digi International Embedded Product Management